Final Product Change Notification

202106007F01 : Assembly Site Transfer from TFME to ASECL for SOICN8 Package

Note: This notice is NXP Company Proprietary.

Issue Date: Jun 24, 2021 **Effective date:**Sep 22, 2021

Change Category

☐ Wafer Fab Process
☐ Assembly Process
☐ Product Marking
☐ Test Process
☐ Design
☐ Wafer Fab Materials
☑ Assembly Materials
☐ Mechanical Specification
☐ Test Equipment
☐ Errata
☐ Wafer Fab Location
☑ Assembly Location
☐ Packing/Shipping/Labeling
☐ Test Location
☐ Electrical spec./Test coverage
☐ Firmware
☐ Other

PCN Overview

Description

NXP Semiconductor is announcing the assembly site transfer for package SOICN8 from TongFu Microeletronics Co.,Ltd, Nantong. China (TFME) Assembly Facility to ASE-CL, CHUNG-LI, TAIWAN (ASECHUNG) Assembly Facility.

The change in assembly site also includes change in Lead frame , molding compound and epoxy.

Reason

TongFu Microeletronics Co.,Ltd, Nantong. China(TFME) assembly facility will not support SOICN8 package assembly, assembly site will be transferred to ASE-CL, CHUNG-LI, TAIWAN (ASECHUNG) for supplier assurance.

Identification of Affected Products
Top Side Marking
There is no change to orderable part number.
Change in package trace code is explained under the 'Remarks' section below.

Product Availability

Sample Information
Samples are available upon request
Samples with part number PC9S08QD2MSC will be provided upon request.
Production
Planned first shipment Sep 24, 2021

Anticipated Impact on Form, Fit, Function, Reliability or Quality

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No Impact on form, fit, function, reliability or quality
Data Sheet Revision
No impact to existing datasheet
Disposition of Old Products
Existing inventory will be shipped until depleted

Additional information

Self qualification: view online
Additional documents: view online

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by Jul 24, 2021.

Remarks

The assembly site is reflected in the package trace code.
The format for the NXP standard trace code:
SOICN8: ALYWZ or LYWZ

A=Assembly Location, L=Wafer Lot, YW=Date Code, Z =Assembly Lot Split,
The marking for TFME is A=XN.
The marking for ASECL is A=X.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards. Customer Focus, Passion to Win.

NXP Quality Management Team.

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